

## P-Channel 60V(D-S) MOSFET

Product summary		
$V_{DS}$	-60	V
$R_{DS(ON)}$ (at $V_{GS}=-10V$ ) Typ.	150	m $\Omega$
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$ ) Typ.	200	m $\Omega$
$I_D$ ( $T_A=25^\circ C$ )	-2	A

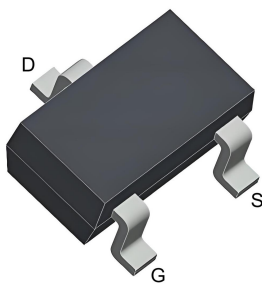
### Features

- Low Gate Charge
- Low  $R_{DS(ON)}$

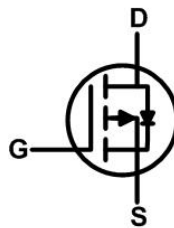
### Applications

- Load Switch
- Switching Circuits
- High Speed line Driver

### Pin Configuration



SOT-23



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECG2309	SOT-23	7"	3000pcs

### Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A=25^\circ C$	-2
		$T_A=70^\circ C$	-1.6
$I_{DM}$	Pulse Drain Current Tested <sup>A</sup>	-8	A
$P_D$	Power Dissipation <sup>B</sup>	$T_A=25^\circ C$	1
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to +150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JA}$	Thermal Resistance-Junction to ambient <sup>B</sup>	125	$^\circ C/W$

**Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)**

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>Static Parameters</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-60	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-60V, V_{GS}=0V$	--	--	-1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	--	--	$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-1.5	-2.5	V
$R_{DS(on)}$	Drain-Source On-State Resistance <sup>C</sup>	$V_{GS}=-10V, I_D=-2A$	--	150	195	m $\Omega$
		$V_{GS}=-4.5V, I_D=-1A$	--	200	290	m $\Omega$
$V_{SD}$	Diode Forward Voltage	$I_{SD}=-2A, V_{GS}=0V$	--	--	-1.2	V
<b>Dynamic Parameters <sup>D</sup></b>						
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=-30V$ $f=1\text{MHz}$	--	310	--	pF
$C_{oss}$	Output Capacitance		--	22	--	pF
$C_{riss}$	Reverse Transfer Capacitance		--	15	--	pF
$Q_g$	Total Gate Charge	$V_{DS}=-30V, I_D=-2A$ $V_{GS}=-10V$	--	5.4	--	nC
$Q_{gs}$	Gate-Source Charge		--	1.1	--	nC
$Q_{gd}$	Gate-Drain Charge		--	1.6	--	nC
$t_{D(on)}$	Turn-on Delay Time	$V_{DD}=-30V$ $I_D=-2A, R_G=3.3\Omega,$ $V_{GS}=-10V$	--	41	--	ns
$t_r$	Turn-on Rise Time		--	22	--	ns
$t_{D(off)}$	Turn-off Delay Time		--	25	--	ns
$t_f$	Turn-off Fall Time		--	32	--	ns

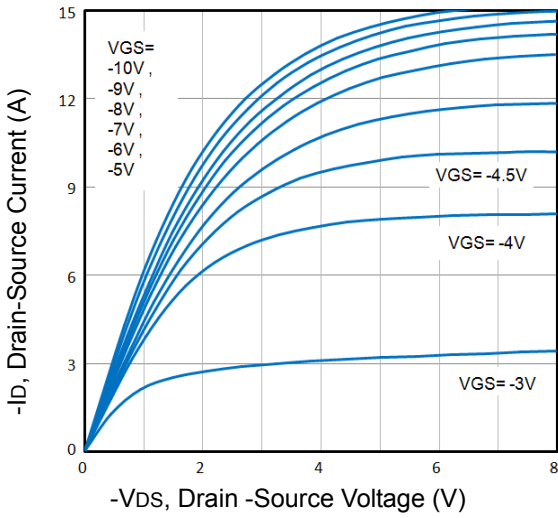
A. Pulse width limited by maximum allowable junction temperature.

B. The data tested by surface mounted on a 1 inch x 1 inch FR-4 board with 2OZ copper.

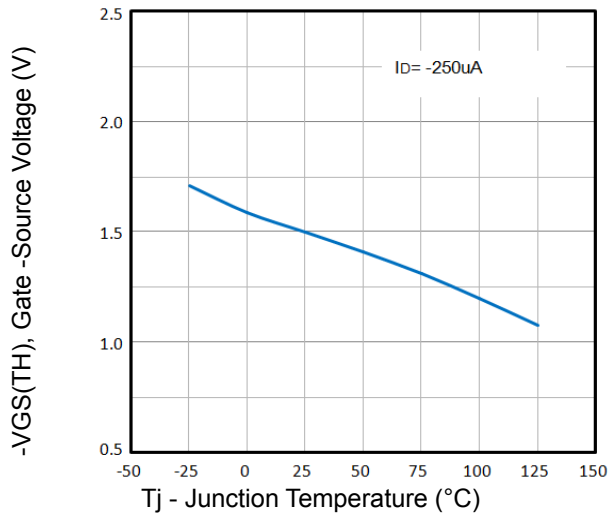
C. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$ .

D. Guaranteed by design, not subject to production testing.

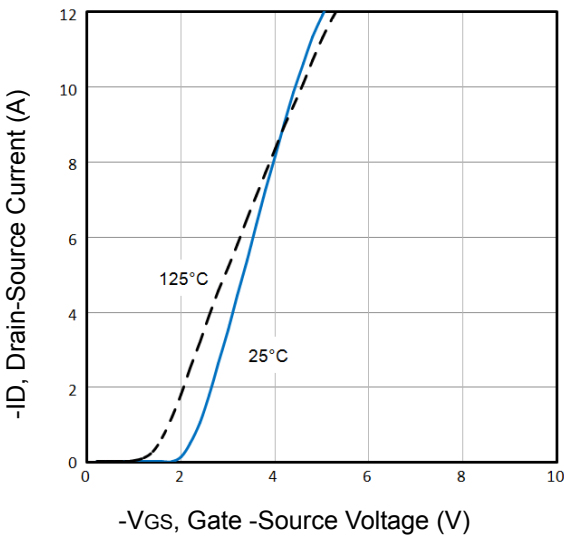
Typical Characteristics



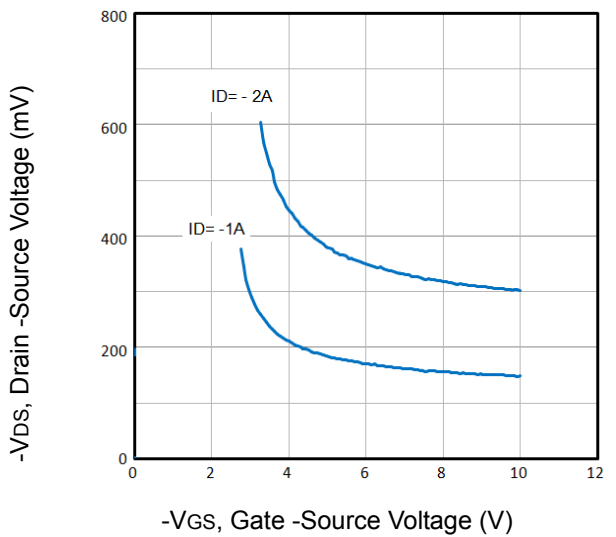
**Fig1.** Typical Output Characteristics



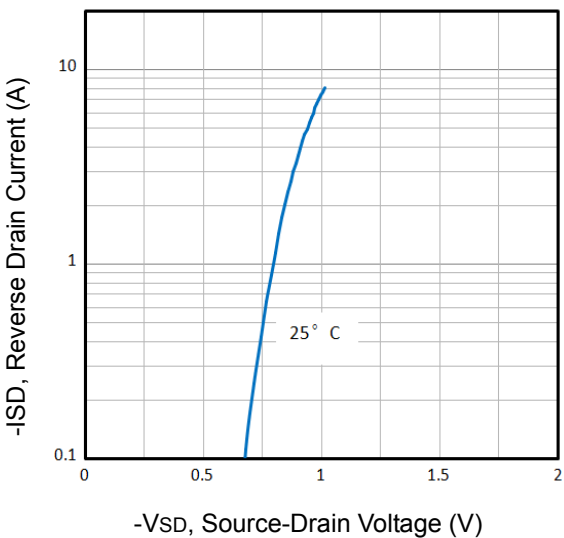
**Fig2.** Normalized Threshold Voltage Vs. Temperature



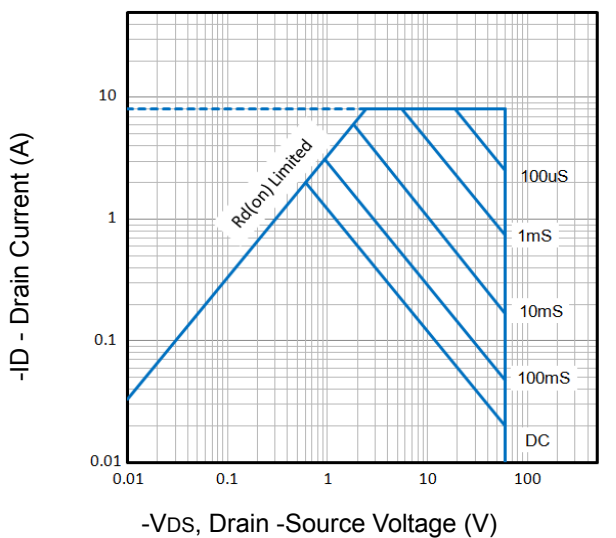
**Fig3.** Typical Transfer Characteristics



**Fig4.** Drain-Source Voltage vs Gate-Source Voltage

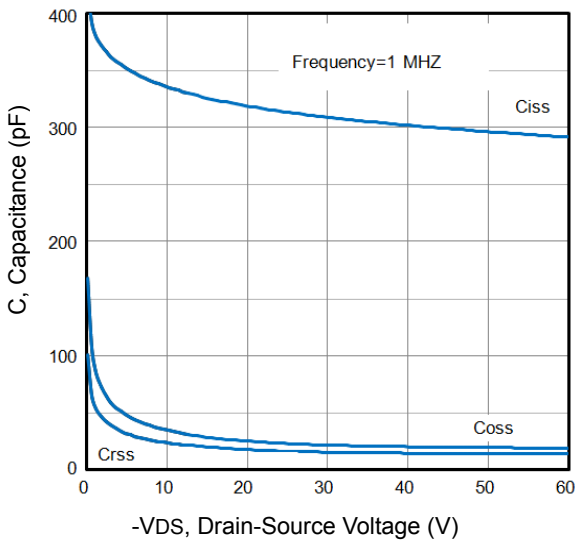


**Fig5.** Typical Source-Drain Diode Forward Voltage

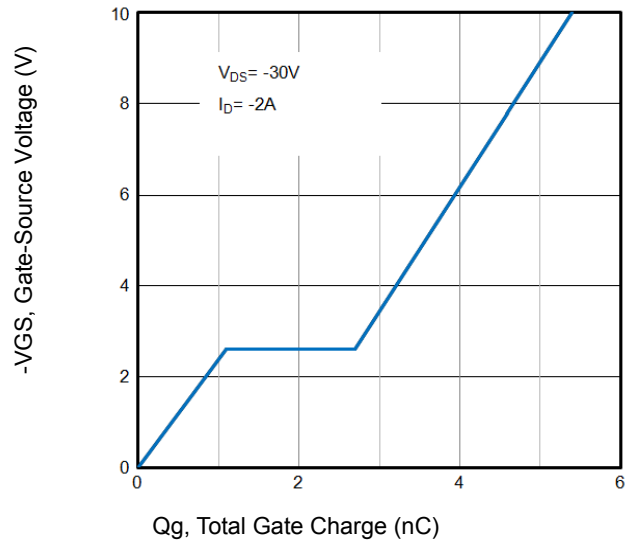


**Fig6.** Maximum Safe Operating Area

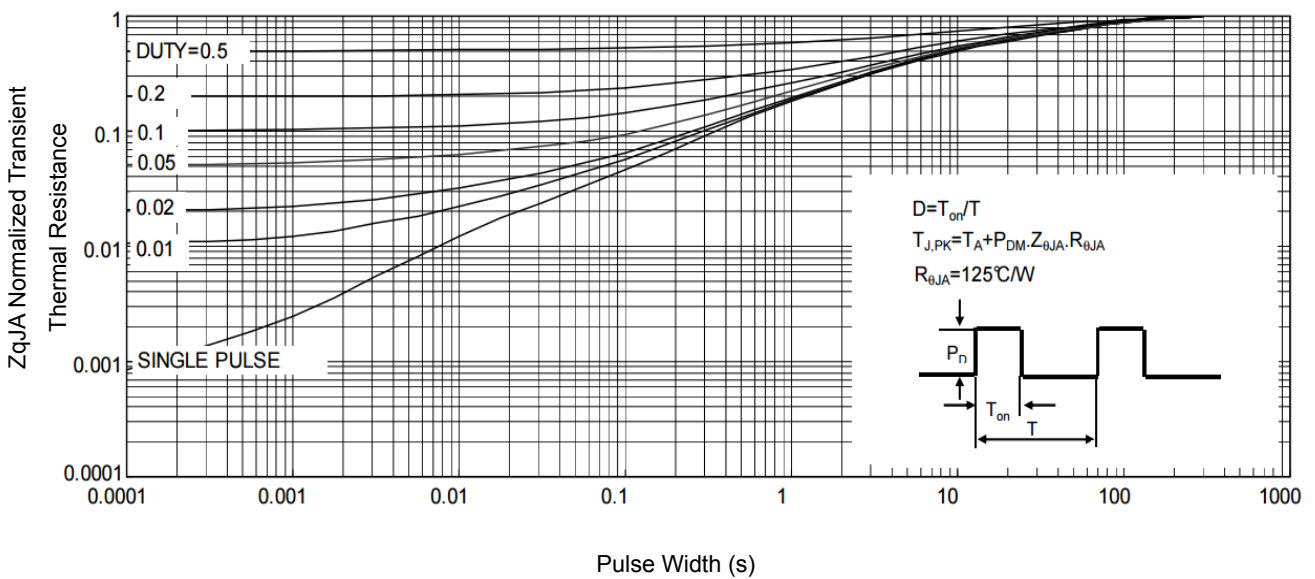
Typical Characteristics



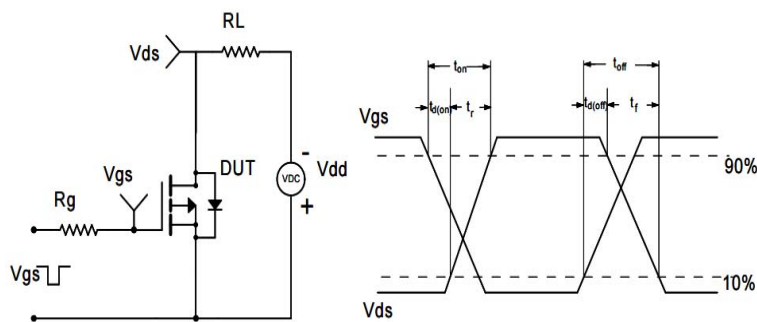
**Fig7.** Typical Capacitance Vs. Drain-Source Voltage



**Fig8.** Typical Gate Charge Vs. Gate-Source Voltage

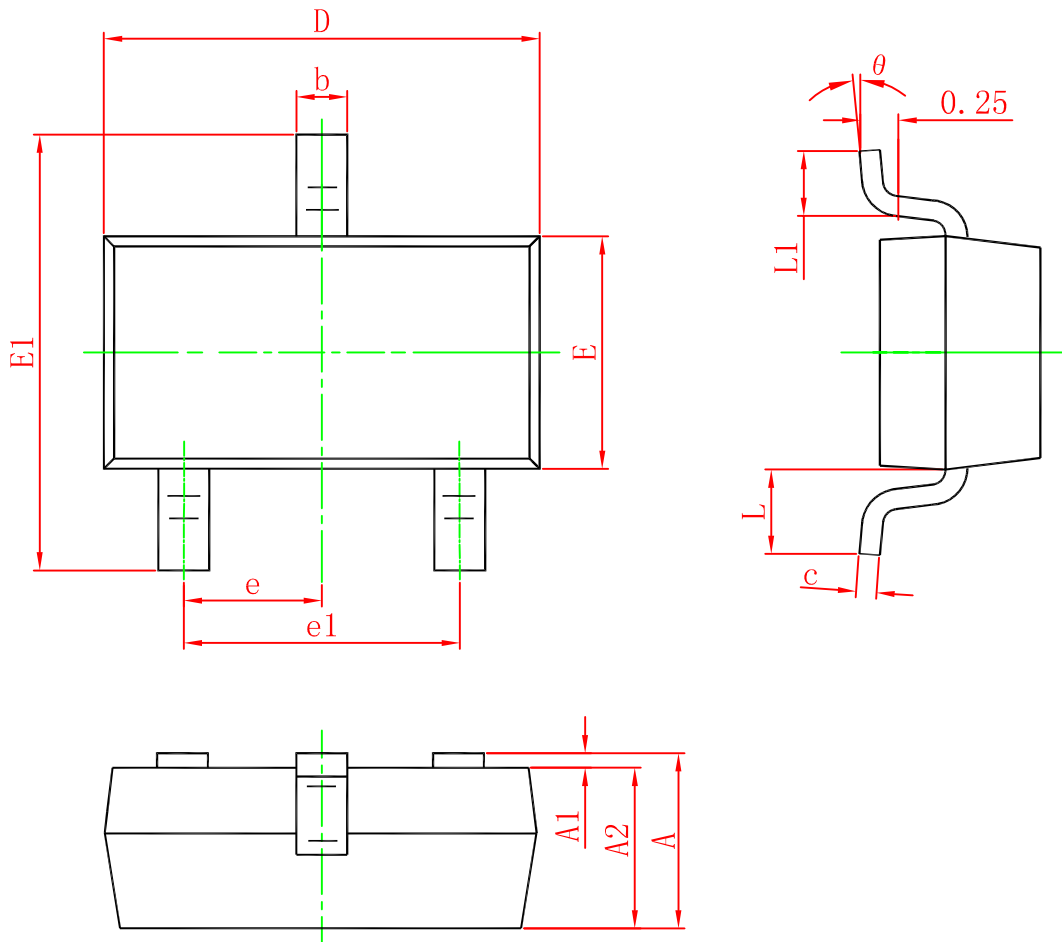


**Fig9.** Normalized Maximum Transient Thermal Impedance



**Fig10.** Switching Time Test Circuit and waveforms

## SOT-23 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
$\theta$	0°	8°	0°	8°